

of **MASER Engineering B.V.**
Enschede

This annex is valid from: **07-07-2015** to **01-10-2017**

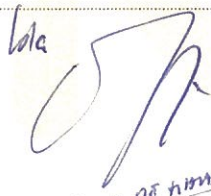
Replaces annex dated: **10-09-2014**

Location where activities are performed under accreditation

Head Office

Capitool 56
7521 PL Enschede
Nederland

| No. | Material or product | Type of activity | Internal reference number |
|-----|-----------------------|---|---|
| 1. | Electronic components | Exposure of (non) heat-dissipating electronic components to calibrated and controlled temperature, humidity and bias conditions | RF_JESD22-A101 conform JESD22-A101 RF_JESD22-A110 conform JESD22-A110 |
| 2. | | Exposure of electronic components to calibrated and controlled temperature and humidity conditions | RF_JESD22-A102 conform JESD22-A102 RF_JESD22-A118 conform JESD22-A118 RF_IEC 60068-2-78 conform IEC 60068-2-78 |
| 3. | | Exposure of electronic components to calibrated and controlled high temperature conditions | RF_JESD22-A103 conform JESD22-A103 RF_IEC 60068-2-2 conform IEC 60068-2-2 RF_MIL-STD-883 m1008 conform MIL-STD-883 method 1008 |
| 4. | | Exposure of electronic components to calibrated and controlled alternating temperature conditions | RF_JESD22-A104 conform JESD22-A104 RF_IEC 60068-2-14 conform IEC 60068-2-14 RF_MIL-STD-883 m1010 conform MIL-STD-883 method 1010 |
| 5. | | Exposure of heat-dissipating electronic components to calibrated and controlled alternating bias and alternating temperature conditions | RF_JESD22-A105 conform JESD22-A105 |

 This annex has been approved by:
Ir. J.C. van der Poel
Chief Executive

of **MASER Engineering B.V.**
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|-----|-----------------------|--|---|
| 6. | Electronic components | Exposure of (non) heat-dissipating electronic components to calibrated and controlled temperature and bias conditions | RF_JESD22-A108 conform JESD22-A108 RF_AEC Q100-008 conform AEC Q100-008 |
| 7. | | Exposure of electronic components to calibrated and controlled low temperature conditions | RF_IEC 60068-2-1 conform IEC 60068-2-1 |
| 8. | | Exposure of electronic components to calibrated and controlled alternating temperature and alternating humidity conditions | RF_IEC 60068-2-30 conform IEC 60068-2-30 |
| 9. | | Exposure of electronic components to calibrated and controlled alternating humidity, alternating temperature and bias conditions | RF_IEC 60068-2-38 conform IEC 60068-2-38 RF_MIL-STD-883 m1004 conform MIL-STD-883 method 1004 |
| 10. | | Exposure of bond wires of electronic components to calibrated and controlled pull forces | RF_MIL-STD-883 m2011 conform MIL-STD-883 method 2011 |
| 11. | | Exposure of bond wires, dies or solderballs of electronic components to calibrated and controlled shear forces | RF_MIL-STD-883 m2019 conform MIL-STD-883 method 2019 RF_AEC Q100-001 conform AEC Q100-001 RF_AEC Q100-010 conform AEC Q100-010 RF_JESD22-B116 conform JESD22-B116 RF_JESD22-B117 conform JESD22-B117 |